

Title (en)

Method of and apparatus for making heat-sensitive stencil master

Title (de)

Verfahren und Vorrichtung zur Herstellung wärmeempfindlicher Druckschablonen

Title (fr)

Procédé et appareil de fabrication de matrice de stencil thermosensible

Publication

EP 1053869 A3 20030205 (EN)

Application

EP 00110725 A 20000519

Priority

JP 14130099 A 19990521

Abstract (en)

[origin: EP1053869A2] A heat-sensitive stencil master is made by imagewise perforating a heat-sensitive stencil master material by use of a thermal head having a plurality of heater elements which are arranged in a main scanning direction and are respectively energized through discrete electrodes while the stencil master material is fed in a sub-scanning direction. A thermal head in which each of the heater elements is divided into at least two segments which are connected to a common discrete electrode to be energized simultaneously with each other is used and each picture element of the stencil master is formed by two or more small perforations formed by the segments of each heater element.

IPC 1-7

B41C 1/14; **B41J 2/345**

IPC 8 full level

B41J 2/345 (2006.01); **B41C 1/055** (2006.01); **B41C 1/14** (2006.01)

CPC (source: EP)

B41C 1/144 (2013.01)

Citation (search report)

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Designated contracting state (EPC)

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